Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

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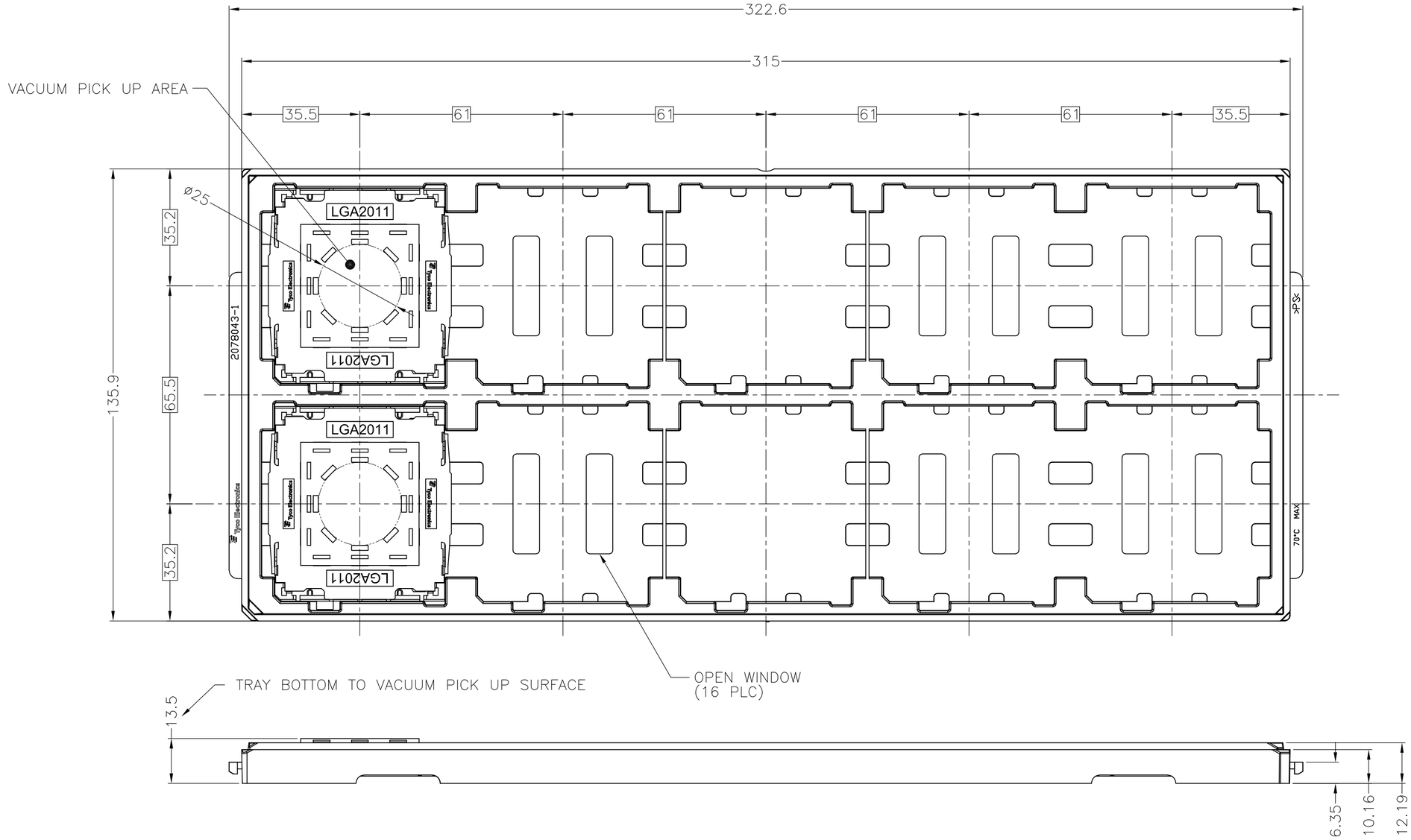
LOC	DIST
J	—

REVISIONS 変更

P	LTR	DESCRIPTION	DATE	DWN	APVD
	F2	REVISED	20MAR'15	J.W	C.W



PART NUMBER	SOCKET NAME	DESCRIPTION
2-1554653-1	LGA2011-0	Au PL ON Pd-Ni PL △3
1-1554653-1	LGA2011-0	0.76 um MIN Au PL
1554653-1	LGA2011-0	0.38 um MIN Au PL

1. MATERIAL
   ① HOUSING : HIGH TEMP, THERMO-PLASTIC, UL94V-0, BLACK
   ② CONTACT : COPPER ALLOY
      FINISH : Au PL. AT CONTACT AREA ON OVERALL OVER Ni UNDER PL. 0.00127 MIN.
   ③ SOLDER BALL : Sn/Ag/Cu
   ④ CAP : HIGH TEMP. THERMO-PLASTIC, UL94V-0, BLACK
△1 INDICATED DATE CODE ON THE HSG
△3 Au PL. ON Pd-Ni ALLOY PL. AT CONTACT AREA ON OVERALL OVER Ni UNDER PL. 0.00127 MIN.
4. PACKAGE TYPE: HARD TRAY, BLUE

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DIMENSIONS: 単位：耗 mm

TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差
0 PLC ± ±0.5
1 PLC ± ±3°
2 PLC ±
3 PLC ±
4 PLC ±
ANGLES ±

MATERIAL 材料 –
FINISH 仕上 –

DWN	J.MIZUSHIMA	05JUL2010
CHK	H.TAGUCHI	05JUL2010
APVD	T.NAKASHIMA	05JUL2010
PRODUCT SPEC 製品規格	108-78750	
APPLICATION SPEC 取付適用規格	114-5474	
WEIGHT	19.1g	

TE Connectivity

NAME 名称: SOCKET ASSY LGA2011-0

SIZE	CAGE CODE	DRAWING NO 番号	RESTRICTED TO
A2	00779	C-1554653	–

CUSTOMER DRAWING | SCALE 尺度 NTS | SHEET 1 OF 6 | REV F2

1554653

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LOC	DIST
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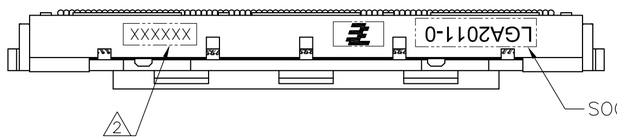
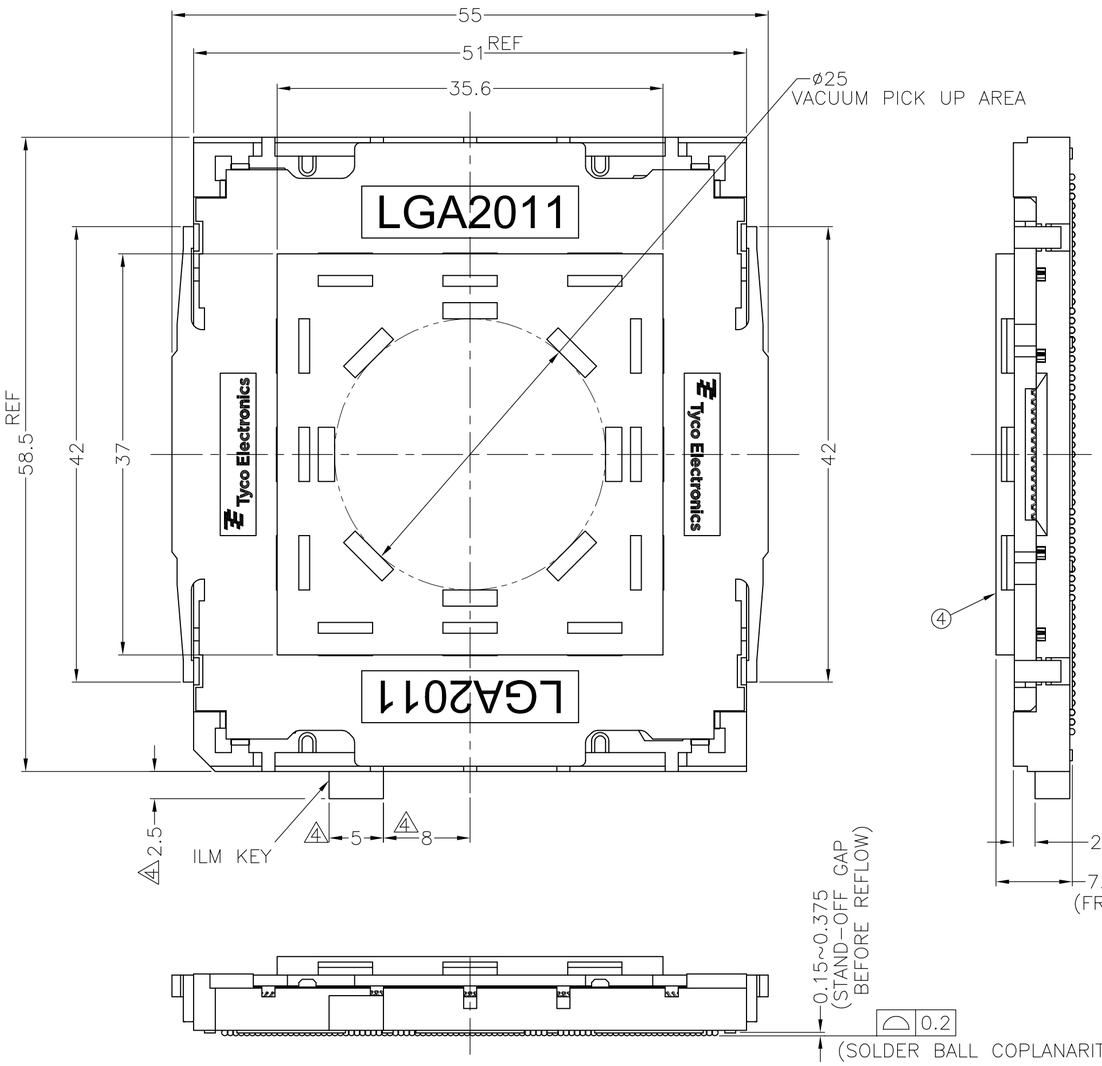
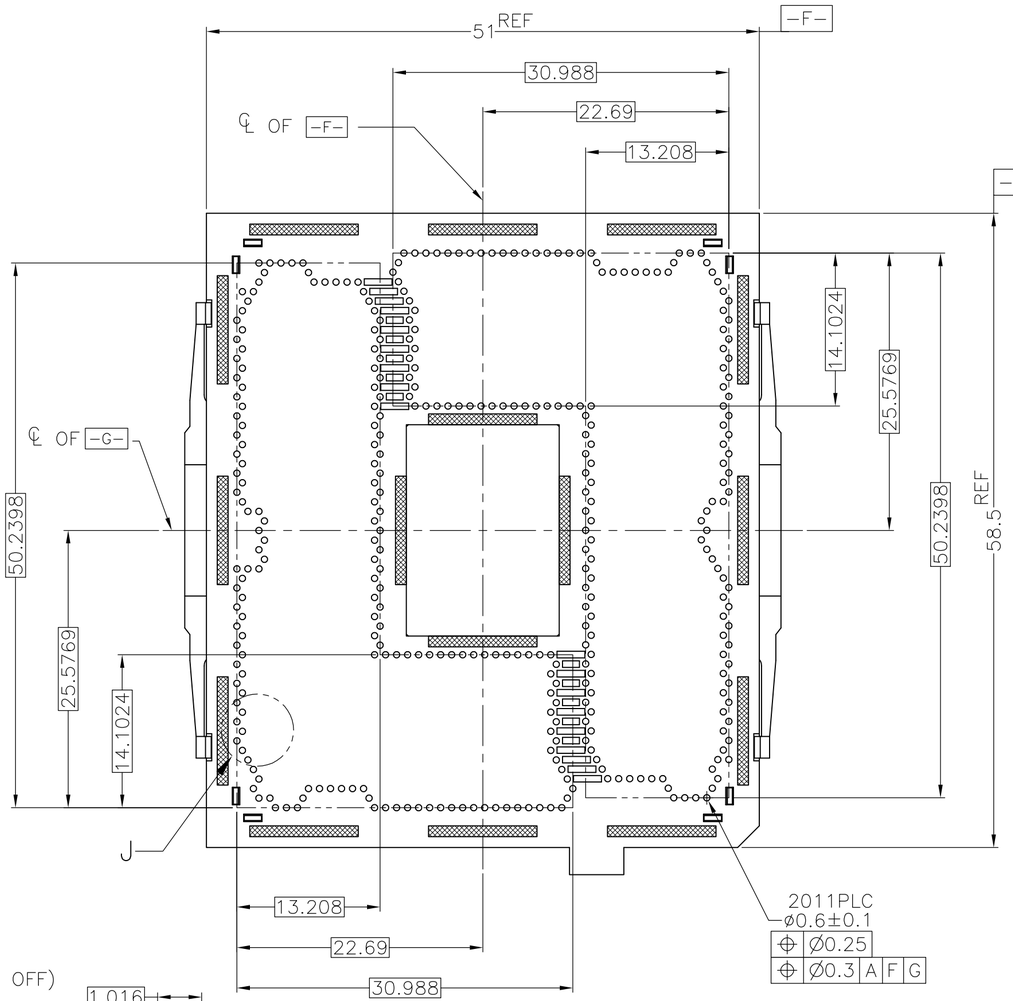
REVISIONS 変更

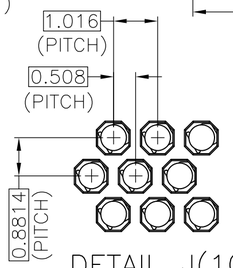
P	LTR	DESCRIPTION	DATE	DWN	APVD
	–	SEE SHEET 1	–	—	—



SOCKET NAME







DETAIL J(10:1)

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DIMENSIONS: 単位：耗 mm

TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差

0 PLC	±0.3
1 PLC	±3°
2 PLC	
3 PLC	
4 PLC	
ANGLES	

MATERIAL 材料 —

FINISH 仕上 —

DWN	—
CHK	—
APVD	—
PRODUCT SPEC 製品規格	—
APPLICATION SPEC 取付適用規格	—
WEIGHT	—

TE Connectivity

NAME 名称: SOCKET ASSY LGA2011-0

SIZE	CAGE CODE	DRAWING NO 番号	RESTRICTED TO
A2	00779	C-1554653	—

CUSTOMER DRAWING

SCALE 尺度 NTS | SHEET 2 OF 6 | REV F2

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LOC	DIST
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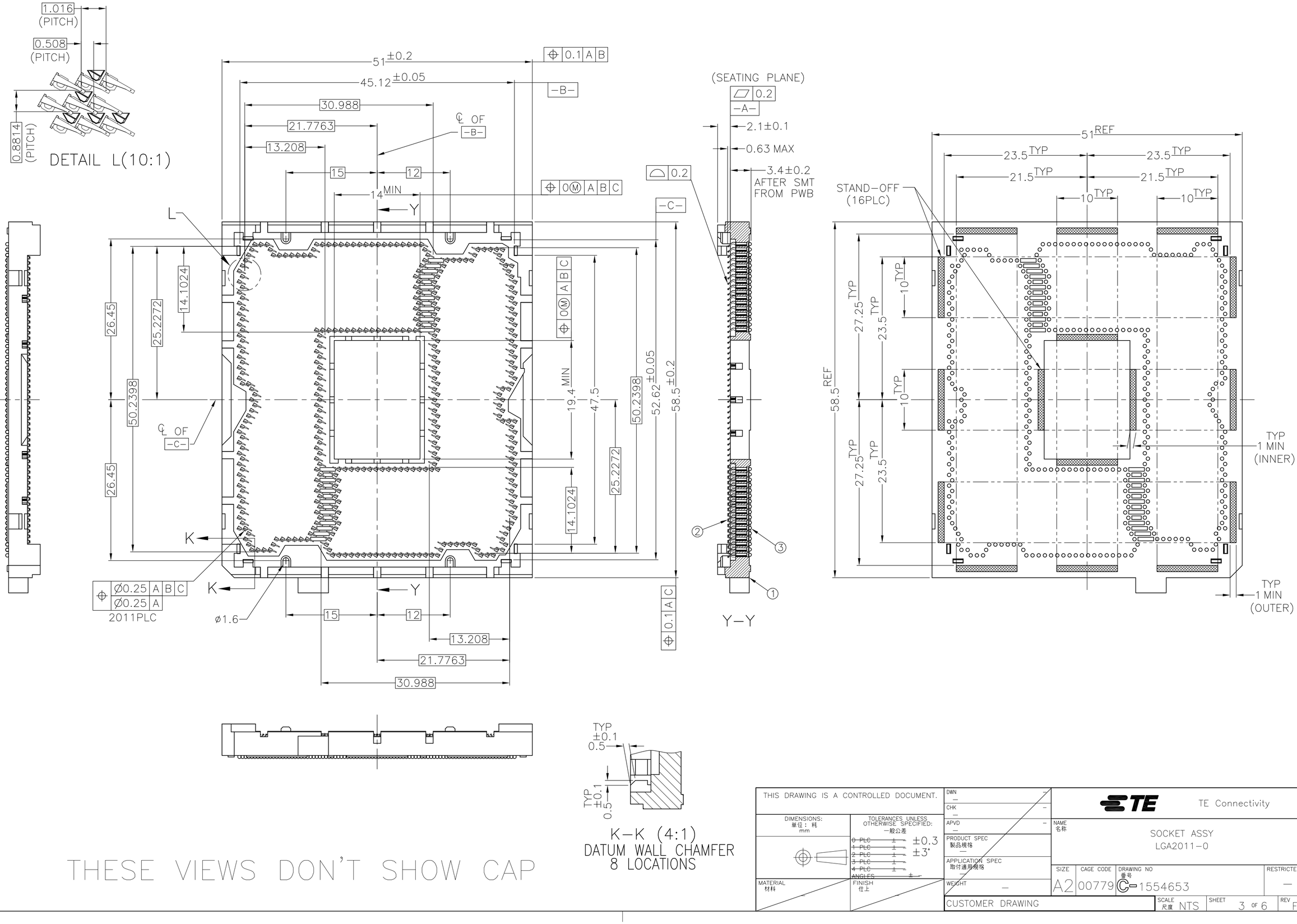
REVISIONS 変更

P	LTR	DESCRIPTION	DATE	DWN	APVD
	–	SEE SHEET 1	–	—	—



THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN —	TE Connectivity		
DIMENSIONS: 単位： 耗 mm	TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差 0 PLC ±– ±0.3; 1 PLC ±–; 2 PLC ±–; 3 PLC ±–; 4 PLC ±–; ANGLES ±– ±3°	CHK —	NAME 名称	SOCKET ASSY LGA2011–0	
		APVD —			
		PRODUCT SPEC 製品規格 —			
		APPLICATION SPEC 取付適用規格 —	SIZE A2	CAGE CODE 00779	DRAWING NO 番号 C–1554653
MATERIAL 材料 —	FINISH 仕上 —	WEIGHT —			RESTRICTED TO —
		CUSTOMER DRAWING	SCALE 尺度 NTS	SHEET 3 OF 6	REV F2

1554653

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LOC	DIST
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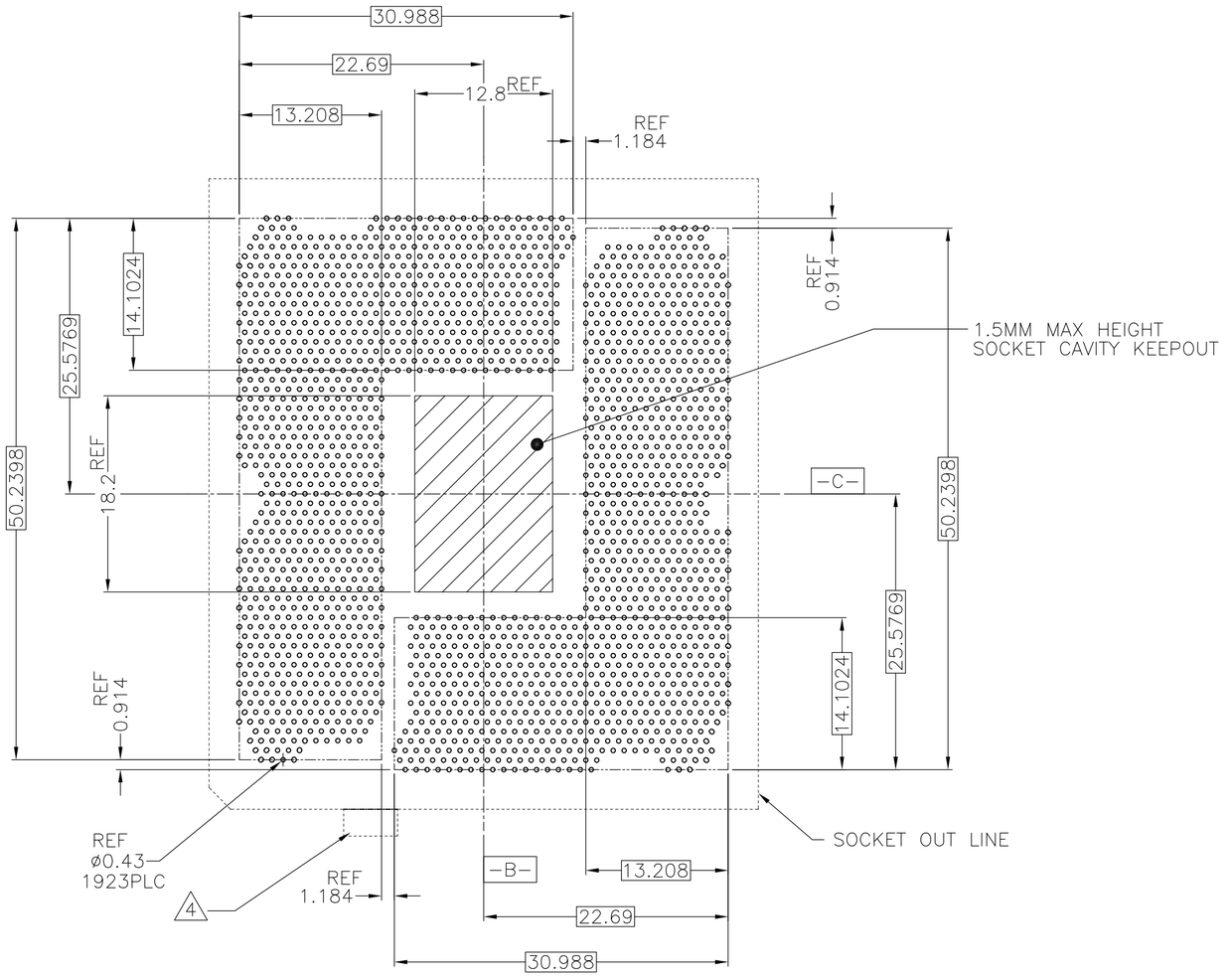
REVISIONS 変更

P	LTR	DESCRIPTION	DATE	DWN	APVD
	–	SEE SHEET 1	–	—	—



REFERENCE PATTERN LAYOUT

FOR GENERAL BOARD DESIGN, PLEASE REFER TO THE THERMAL AND MECHANICAL DESIGN GUIDELINES(TMDG) PROVIDED BY INTEL CORPORATION

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DIMENSIONS: 単位： 耗 mm

TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差
0 PLC ± – ±0.3
1 PLC ± –
2 PLC ± – ±3°
3 PLC ± –
4 PLC ± –
ANGLES ± –

MATERIAL 材料 –
FINISH 仕上 –

DWN – —
CHK – —
APVD – —
PRODUCT SPEC 製品規格 —
APPLICATION SPEC 取付適用規格 —
WEIGHT —

TE Connectivity

NAME 名称: SOCKET ASSY LGA2011–0

SIZE	CAGE CODE	DRAWING NO 番号	RESTRICTED TO
A2	00779	C-1554653	—

CUSTOMER DRAWING | SCALE 尺度 NTS | SHEET 4 OF 6 | REV F2

1554653

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LOC	DIST
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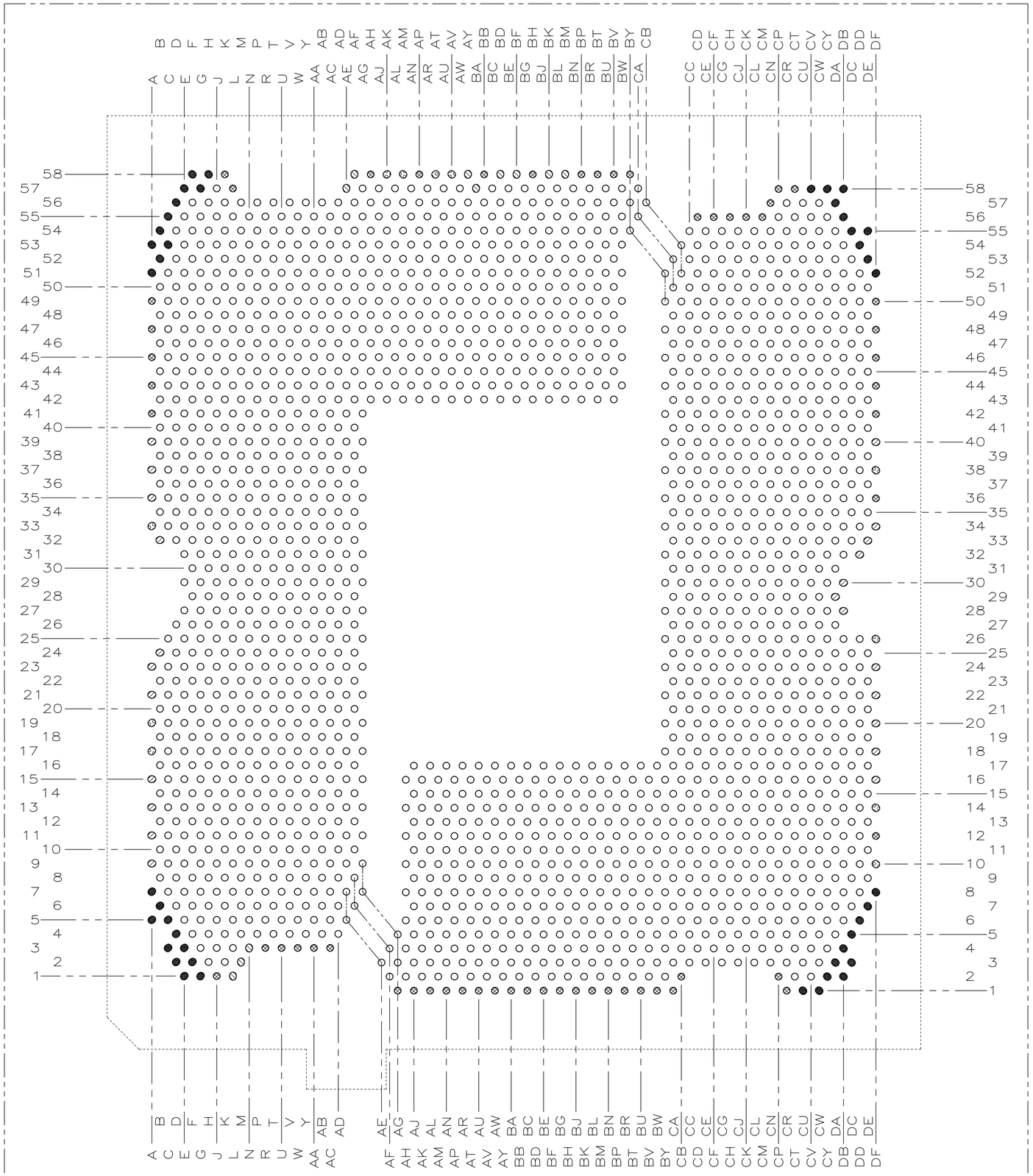
REVISIONS 変更

P	LTR	DESCRIPTION	DATE	DWN	APVD
	–	SEE SHEET 1	–	—	—



LOCATION ID AND REFFERENCE LAND PATTERN GUIDANCE

NOTE(APPLIED TO SHEET 5 OF 5):

1. NON-CRITICAL TO FUNCTION PADS IN THE FOUR CORNER: 0.43X0.51 OBLONG SMD(SOLDER MASK DEFINED) PAD WHICH IS ORIENTED AT 45° TO THE SOCKET EDGE. THE PAD END CLOSEST TO THE CENTER OF THE SOCKET SHOULD HAVE ø0.43±0.025 SRO(SOLDER RESIST OPENING) WHICH IS A CRITICAL TO FUNCTION DIMENSION.
2. CRITICAL TO FUNCTION PADS ORIENTED AT 90°: 0.43X0.51 OBLONG SMD PAD WHICH IS ORIENTED AT 90° TO THE SOCKET EDGE. THE PAD END CLOSEST TO THE CENTER OF THE SOCKET SHOULD HAVE ø0.43±0.025 SRO.
3. CRITICAL TO FUNCTION PADS ORIENTED AT 45°: 0.43X0.51 OBLONG SMD PAD WHICH IS ORIENTED AT 45° TO THE SOCKET EDGE. THE PAD END CLOSEST TO THE CENTER OF THE SOCKET SHOULD HAVE ø0.43±0.025 SRO.
4. CRITICAL TO FUNCTION PADS EXCEPT FOR DEFINED IN 2 3 : CIRCULAR MD(METAL DEFINED) OR SMD IF POWER/GROUND PAD IN A FLOOD PLANE.ø0.43±0.025 SRO. FOR MD PADS ONLY A THICK TRANCE 0.25 MIN WIDTH NO GREATER THAN 0.43.
5. ALL PADS EXCEPT FOR DEFINED IN 1 2 3 4 : CIRCULAR MD PAD WITH ø0.43±0.025 SRO

MARK	DESCRIPTION	LOCATION ID	PAD
■	1 NON-CRITICAL TO FUNCTION PADS IN THE FOUR CORNER (43PCS)	A53,B54,C55,D56,E57,F58,A51,B52 C53,G57,H58,CU1,CW1,CY2DA3,DB4 DC5,DD6,DE7,DF8,DB2,DC3,E1,D2, C3,A5,G1,F2,E3,D4,C5,B6,A7,DF52, DE53,DD54,DC55,DB56,DA57,CY58, CV58,DE55,DB58	THICK TRACE, SRO ±0.025 ø0.43, 0.MIN .25, 0.REF 0.43, SMD PAD, 0.REF 0.51
▨	2 CRITICAL TO FUNCTION PADS ORIENTED AT 90° (34PCS)	L1,M2,N3,AE57,AF58,AY58,BA57 BD58,BF58,BK58,BM58,DF40,DF34 DE33,DD32,DB30,DA29,DB28,DF24 DF22,DF20,DF18,DF16,A9,A11,A13 A15,A21,A23,B24,B32,A35,A37,A39	
▨	3 CRITICAL TO FUNCTION PADS ORIENTED AT 45° (11PCS)	AM58,AV58,DF38,DF26,DF14,DF10 A33,A19,A17,AK58,AT58	
▩	4 CRITICAL TO FUNCTION PADS EXCEPT FOR DEFINED IN 2 3 (57PCS)	CT58,CP58,CN57,CM56,CK56,CH56 CF56,CD56,BY58,BV58,BT58,BP58 BH58,BB58,AP58,AH58,K58,L57,J1 R3,U3,W3,AA3,AC3,AG1,AJ1,AL1,AN1 AR1,AU1,AW1,BA1,BC1,BE1,BG1,BJ1 BL1,BN1,BR1,BU1,BW1,CA1,CB2,CP2 CR1,A49,A47,A45,A43,A41,DF12 DF36,DF42,DF44,DF46,DF48,DF50	MD OR SMD PAD ø0.43±0.025
□	5 ALL PADS EXCEPT FOR DEFINED IN 1 2 3 4	ALL PADS EXCEPT FOR DEFINED IN 1 2 3 4	MD PAD ø0.43±0.025

FOR GENERAL BOARD DESIGN, PLEASE REFER TO THE THERMAL AND MECHANICAL DESIGN GUIDELINES(TMDG) PROVIDED BY INTEL CORPORATION

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DIMENSIONS: 単位：耗 mm

TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差
0 PLC ± —
1 PLC ± —
2 PLC ± —
3 PLC ± —
4 PLC ± —
ANGLES ± —

MATERIAL 材料 —
FINISH 仕上 —

DWN —
CHK —
APVD —
PRODUCT SPEC 製品規格 —
APPLICATION SPEC 取付適用規格 —
WEIGHT —

TE Connectivity

NAME 名称: SOCKET ASSY LGA2011-0

SIZE	CAGE CODE	DRAWING NO 番号	RESTRICTED TO
A2	00779	C-1554653	—

CUSTOMER DRAWING | SCALE 尺度 NTS | SHEET 5 OF 6 | REV F2

1554653

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LOC	DIST
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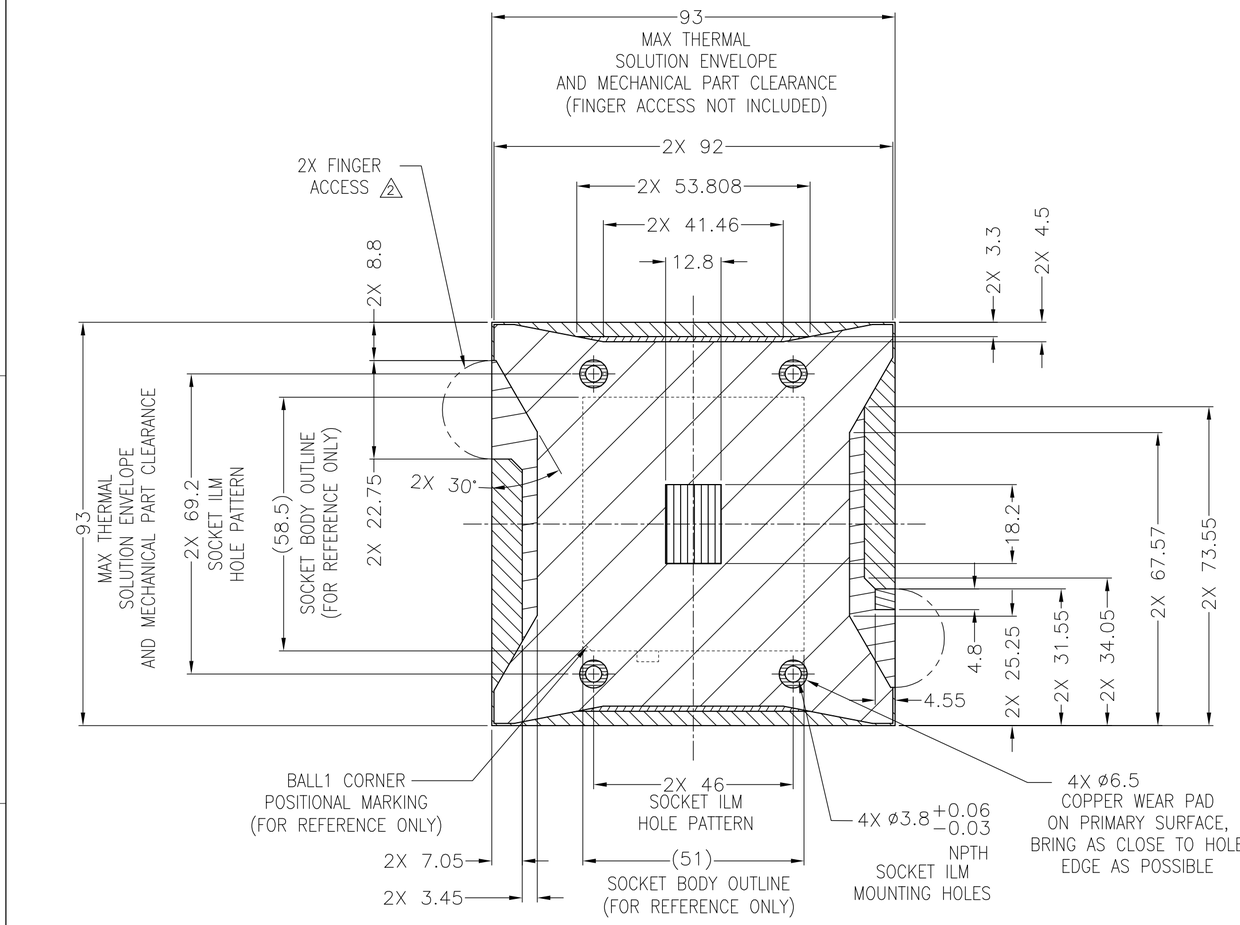
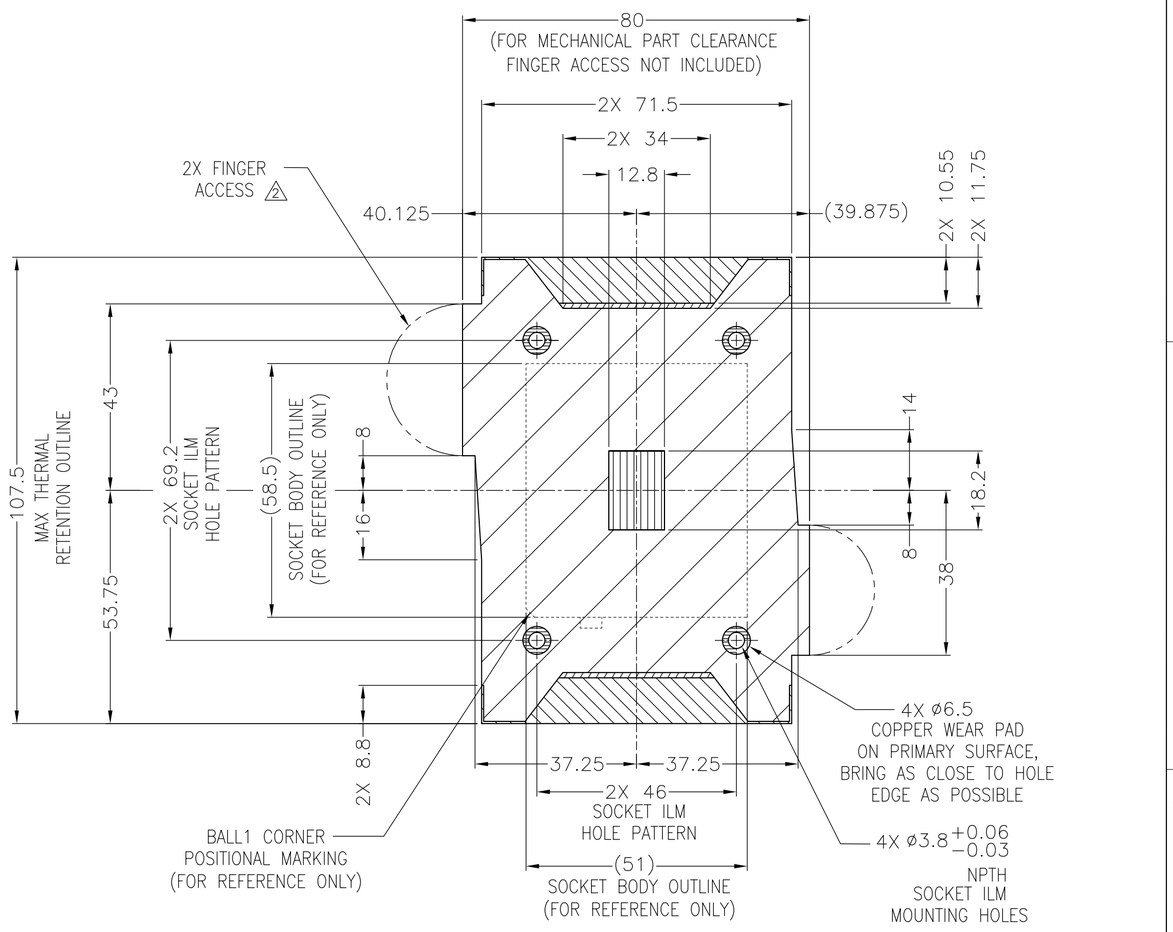
REVISIONS 変更

P	LTR	DESCRIPTION	DATE	DWN	APVD
	–	SEE SHEET 1	–	—	—



FOR ILM ASSY WIDE TYPE



FOR ILM ASSY NARROW TYPE

COMPONENT KEEP-INS AND MECHANICAL COMPONENT KEEP-OUTS

FOR REFERENCE ONLY, PLEASE REFER TO THE THERMAL AND MECHANICAL DESIGN GUIDELINES(TMDG) PROVIDED BY INTEL CORPORATION

NOTES (APPLIED TO SHEET 6 OF 6):
1. DIMENSIONS STATED IN MILLIMETERS AND DEFINE ZONES, FOR UNDEFINED DIMENSINS, REFER TO THERMAL AND MECHANICAL DESIGN GUIDELINE PROVIDED BY INTEL CORPORATION.
2. SIZE & HEIGHT OF FINGER ACCESS TO BE DETERMINED BY SYSTEM/BOARD ARCHITECT. THIS IS ILM MECHANICAL CLEARANCE ONLY AND FINGER AND/OR TOOL. ACCESS SHOULD BE DETERMINED SEPARATELY.

LEGEND	
	0.0MM MAX COMPONENT HEIGHT, NO COMPONENT PLACEMENT, SOCKET, ILM, AND FINGER ACCESS KEEPIN ZONE
	7.2MM MAX COMPONENT HEIGHT.
	0.0MM MAX COMPONENT HEIGHT, NO COMPONENT PLACEMENT, NO ROUTE ZONE
	1.67MM MAX COMPONENT HEIGHT AFTER REFLOW 1.50MM MAX (MMC) COMPONENT HEIGHT BEFORE REFLOW
	1.6MM MAX COMPONENT HEIGHT.
	1.5MM MAX COMPONENT HEIGHT.
	1.9MM MAX COMPONENT HEIGHT.

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DIMENSIONS: 単位：耗 mm

TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差
0 PLC ± –
1 PLC ± –
2 PLC ± –
3 PLC ± –
4 PLC ± –
ANGLES ±

MATERIAL 材料 –
FINISH 仕上 –

DWN – —
CHK – —
APVD – —
PRODUCT SPEC 製品規格 —
APPLICATION SPEC 取付適用規格 —
WEIGHT –

TE Connectivity

NAME 名称: SOCKET ASSY LGA2011-0

SIZE	CAGE CODE	DRAWING NO 番号	RESTRICTED TO
A2	00779	C-1554653	—

CUSTOMER DRAWING | SCALE 尺度 NTS | SHEET 6 OF 6 | REV F2

1554653